2.0mm x 1.6mm



Features

- ±10ppm/±20ppm (Tolerance/Stability)
- Ultra-Miniature Package
- AT-Cut Fundamental
- Tape and Reel

Applications

- Office Automation
- Audio/Visual Bluetooth
- Small Communication Devices
- SSD
- USB

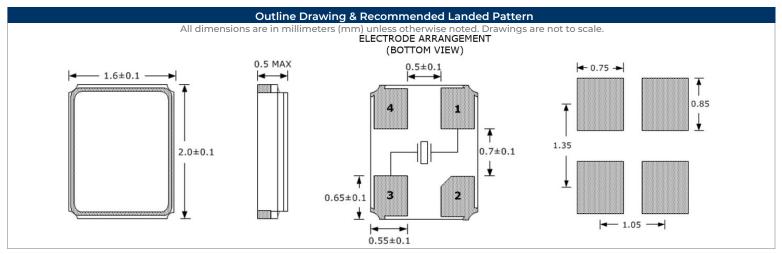


Part Numbering Guide

SCX810-26.000M



| Electrical Parameters | Units | Minimum | Typical | Maximum | Remarks |
|---------------------------------|-------|---------|---------|---------|---------------------|
| Frequency Range | MHz | | 26 | | AT-Cut Fundamental. |
| Frequency Tolerance at +25°C | ppm | -10 | | 10 | |
| Frequency Stability vs. Op Temp | ppm | -20 | | 20 | |
| Frequency Stability vs. Aging | ppm | -2 | | 2 | First year @ +25°C. |
| Operating Temperature | °C | -40 | | 85 | |
| Storage Temperature | °C | -40 | | 125 | |
| Load Capacitance | pF | | 6 | | |
| Shunt Capacitance | pF | | | 5 | |
| Drive Level | μW | | 50 | 100 | |
| Insulation Resistance | МΩ | 500 | | | @ 100VDC ± 15V. |
| Equivalent Series Resistance | Ω | | | 50 | |





| Environmental Specific | ations | Mechanical Specifications | | |
|------------------------|---------------------------------------|------------------------------|---------------------------------------|--|
| Temperature Cycling | MIL-STD-883, Method 1010, Condition B | Mechanical Shock | MIL-STD-202, Method 213, Condition B | |
| Fine Leak Test | MIL-STD-883, Method 1014, Condition A | Vibration | MIL-STD-883, Method 2007, Condition A | |
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C | Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K | |
| Moisture Resistance | MIL-STD-883, Method 1004 | Resistance to Solvents | MIL-STD-202, Method 215 | |
| Moisture Sensitivity | J-STD-020, MSL 1 | Solderability | MIL-STD-883, Method 2003 | |

